Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Previously Amended) A package sealing method comprising the following steps of:

providing a case which houses a product and has an opening surface, and a lid that covers the opening surface, which is made of a material that is transparent to a laser beam having a predetermined wavelength;

interposing a bonding member between the case and the lid; and

irradiating the bonding member with said laser beam through the lid so that the bonding member is melted to bond the case and the lid to each other with intervention of the bonding member.

2. (Previously Amended) The package sealing method according to claim 1, wherein the step of interposing the bonding member is preparatively formed on the case or the lid.

3. (Previously Amended) The package sealing method according to claim 1, wherein the case and the lid are fixed to each other by pressure, and thereafter, the bonding member is irradiated with said laser beam.

4. (Canceled).

5. (Previously Amended) A package sealing method comprising the following steps of:

providing a case which houses a product and has an opening surface and a through hole provided in a wall of the case, and a lid that covers the opening surface, which is made of a material that is transparent to a laser beam having a predetermined wavelength;

interposing a bonding member between the case and the lid;

fixing the lid and the case to each other by vacuum suction using the through hole;

irradiating the bonding member with said laser beam through the lid so that the bonding member is melted to bond the case and the lid to each other with intervention of the bonding member;

arranging a metal in the through hole;

irradiating the metal with a laser beam so that the metal is melted to seal the through hole with the molten metal.

6. (Previously Amended) The package sealing method according to claim 5, wherein the laser beam for melting the bonding member and the laser beam for melting the metal have the same wavelength.

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7. (Previously Amended) The package sealing method according to claim 1, wherein said laser beam is scanned, to irradiate the bonding member point by point so that the case and the lid are bonded together.

8. (Previously Amended) The package sealing method according to claim 1, wherein said laser beam is projected through a phase hologram to generate a diffraction light pattern, with which the bonding member is entirely irradiated at one time, so that the case and the lid are bonded together.

9. (Previously Amended) The package sealing method according to claim 8,

wherein part of a light energy of said laser beam incident on the phase hologram is reserved in the zero-th order diffracted beam from the phase hologram, and the diffraction light pattern is positioned by using the zero-th order diffracted beam.

10. (Previously Amended) The package sealing method according to claim 8, wherein said laser beam is converged by a condensing lens, the phase hologram is arranged between the condensing lens and the lid, and a position of the phase hologram is controlled in

an optical axis direction so as to obtain the diffraction light pattern at a desired location with desired dimensions.

11. (Previously Amended) The package sealing method according to claim 1, wherein a temperature distribution over the bonded portion of the case and the lid is monitored during the laser irradiation of the bonding member.

12. (Previously Amended) The package sealing method according to claim 1, wherein the bonding member is preheated before being irradiated with said laser beam.

13. (Previously Amended) An electronic device module manufacturing method for sealing a case housing an electronic device, with a lid, comprising the steps of:

providing a case which houses an electronic device and has an opening surface, and a lid that covers the opening surface, which is made of a material that is transparent to a laser beam having a predetermined wavelength;

interposing a bonding member between the case and the lid; and

irradiating the bonding member with said laser beam through the lid so that the bonding member is melted to bond the case and the lid to each other with intervention of the bonding member.

14-22. (Canceled).